

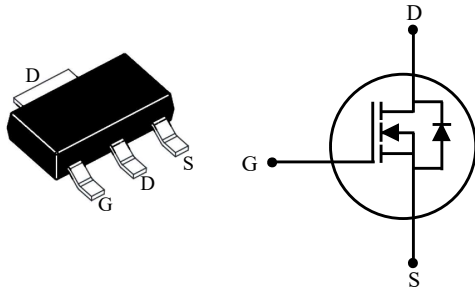


# SMTQ10N1K1LSSEH

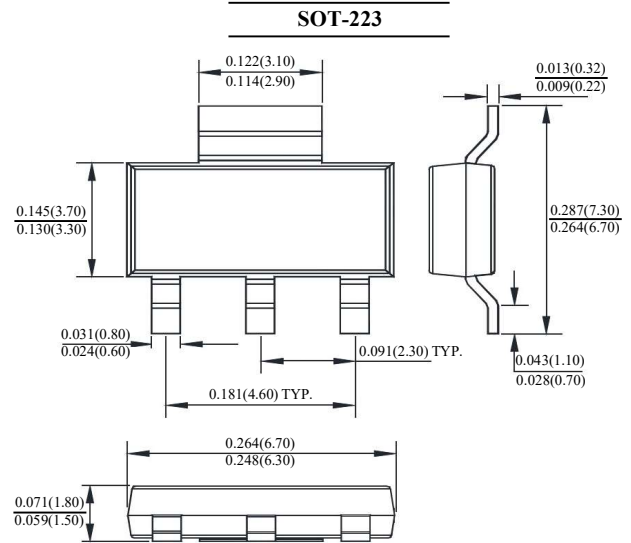
## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

· Suffix "H" indicates Halogen-free parts, ex.SMTQ10N1K1LSSEH



D	Drain
G	Gate
S	Source



**Dimensions in inch and (millimeter)**

### Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	$V_{DS}$	100	V	
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V	
Drain Current	$I_D$	$T_A = 25^\circ\text{C}$	4.0	A
		$T_A = 70^\circ\text{C}$	3.0	A
Pulsed Drain Current	$I_{DM}$	20	A	
Single-Pulse Avalanche Current	$I_{AS}$	5	A	
Single-Pulse Avalanche Energy	$E_{AS}$	3.7	mJ	
Power Dissipation	$P_D$	2.7	W	
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	(Note 3)	100	$^\circ\text{C/W}$
		(Note 4)	45	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{stg}$	- 55 to + 150	$^\circ\text{C}$	

Note :

1. Pulse width  $\leq 100\mu\text{s}$ , Duty Cycle  $\leq 2\%$ , Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})} = 150^\circ\text{C}$ .
2. Limited by  $T_{J(\text{MAX})}$ , starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.3\text{mH}$ ,  $R_g = 25\Omega$ ,  $I_{AS} = 5\text{A}$ ,  $V_{GS} = 10\text{V}$ .
3. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate,  $t < 10\text{s}$ .
4. Device mounted on FR-4 substrate PC board, minimum recommended footprint. Steady state.



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### Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

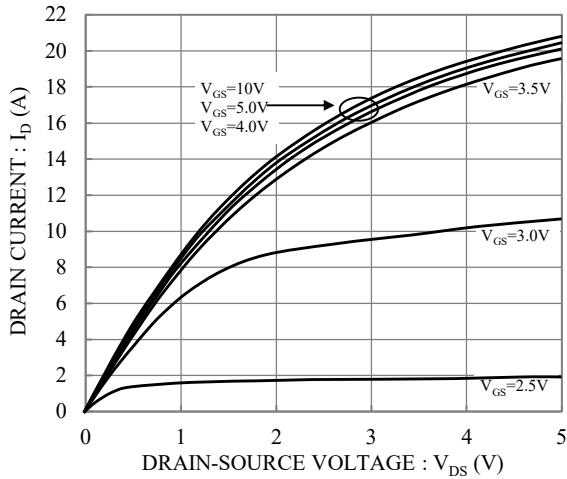
Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
<b>Static</b>						
Drain Source Breakdown Voltage	$I_D = 250\mu\text{A}$	$V_{(BR)DSS}$	100	-	-	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	$V_{GS(th)}$	1.2	-	2.5	V
Zero Gate Voltage Drain Current	$V_{DS} = 80\text{V}$	$I_{DSS}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$V_{GS} = \pm 20\text{V}$	$I_{GSS}$	-	-	$\pm 0.1$	$\mu\text{A}$
Drain-Source On-State Resistance	$V_{GS} = 10\text{V}, I_D = 4\text{A}$	$R_{DS(on)}$	-	106	115	m $\Omega$
	$V_{GS} = 4.5\text{V}, I_D = 3\text{A}$		-	-	125	
<b>Dynamic</b>						
Forward Transfer Admittance	$V_{DS} = 5\text{V}, I_D = 4\text{A}$	$g_{FS}$	-	8	-	S
Gate Resistance	$V_{GS} = 0\text{V}, V_{DS} = 0\text{V}, f = 1\text{MHz}$	$R_g$	-	1.1	-	$\Omega$
Total Gate Charge	$V_{DS} = 50\text{V}, I_D = 4\text{A}, V_{GS} = 4.5\text{V}$	$Q_g$	-	9	-	nC
Gate-Source Charge			$V_{DS} = 50\text{V}, I_D = 4\text{A}, V_{GS} = 10\text{V}$	-	20	
Gate-Drain Charge	$Q_{gd}$	-		2	-	
Input Capacitance	$V_{DS} = 50\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	$C_{iss}$	-	1155	-	
Output Capacitance		$C_{oss}$	-	28	-	
Reverse Transfer Capacitance		$C_{rss}$	-	25	-	
Turn-On Delay Time	$V_{DS} = 50\text{V}, V_{GS} = 10\text{V}, I_D = 4\text{A}, R_g = 3.3\Omega$	$t_{d(on)}$	-	14	-	ns
Turn-On Rise Time		$t_r$	-	4	-	
Turn-Off Delay Time		$t_{d(off)}$	-	13	-	
Turn-Off Fall Time		$t_f$	-	2	-	
<b>Drain-Source Body Diode</b>						
Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 1\text{A}$	$V_{SD}$	-	-	1.2	V
Diode Continuous Forward Current	-	$I_S$	-	-	4	A
Diode Pulse Current	-	$I_{SM}$	-	-	20	A
Reverse Recovery Time	$I_S = 4\text{A}, di/dt = 100\text{A}/\mu\text{s}$	$t_{rr}$	-	21	-	ns
Reverse Recovery Charge		$Q_{rr}$	-	22	-	nC



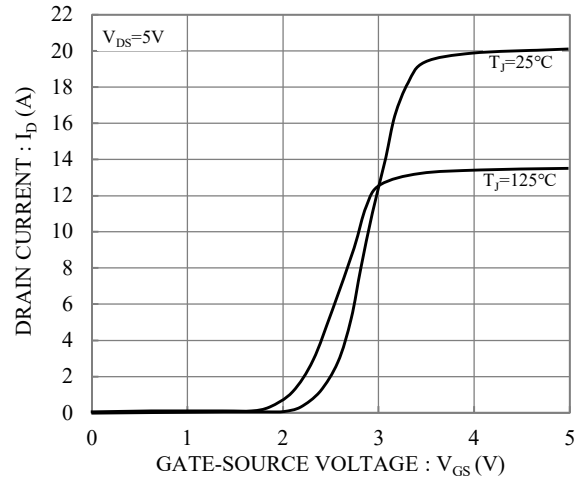
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## N-Channel Enhancement Mode Field Effect Transistor

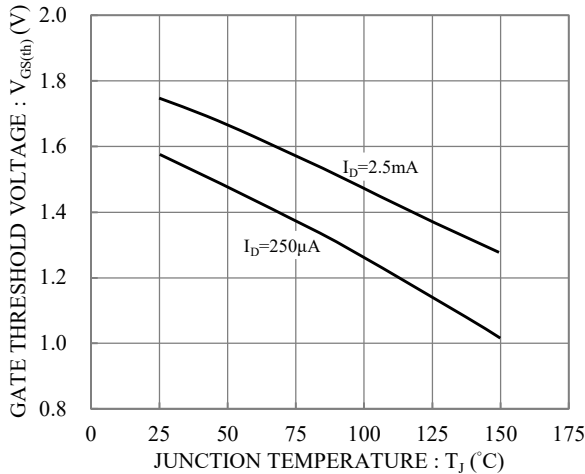
### RATINGS AND CHARACTERISTIC CURVES



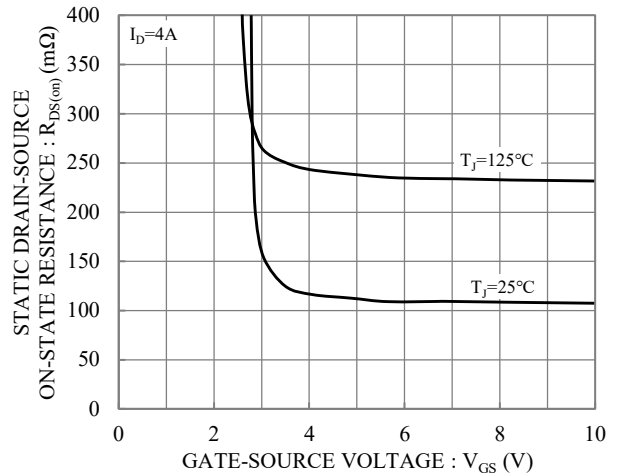
**Fig.1 Typical Output Characteristics**



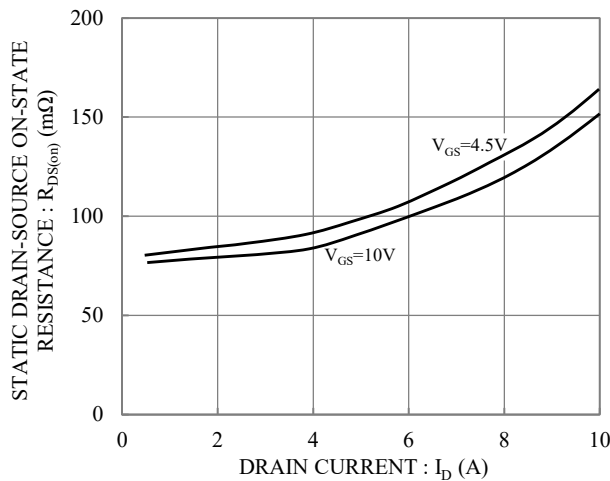
**Fig.2 Typical Transfer Characteristics**



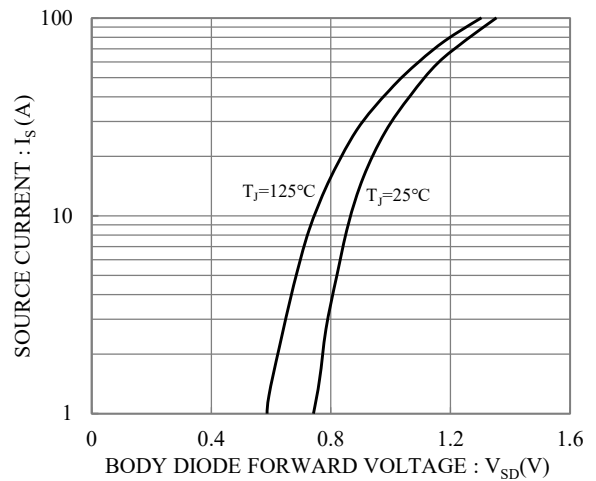
**Fig.3 Gate Threshold Voltage vs. Junction Temperature**



**Fig.4 Static Drain-Source On-State Resistance vs. Gate-Source Voltage**



**Fig.5 Static Drain-Source On-State Resistance vs. Drain Current**

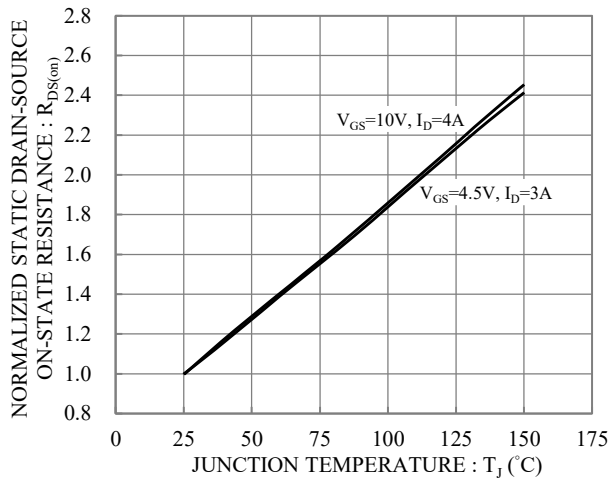


**Fig.6 Body Diode Forward Voltage vs. Source Current**

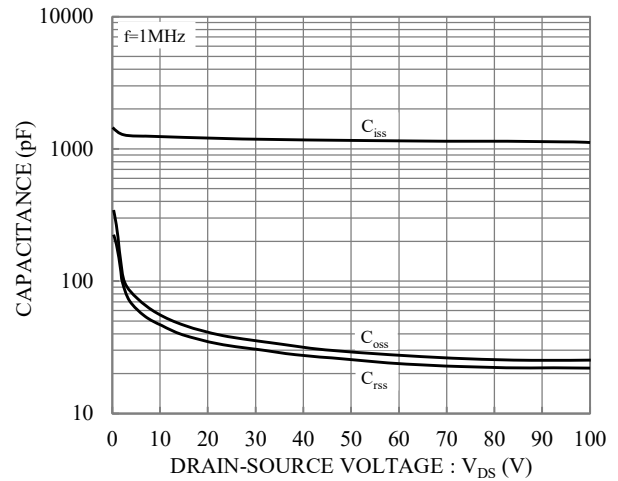


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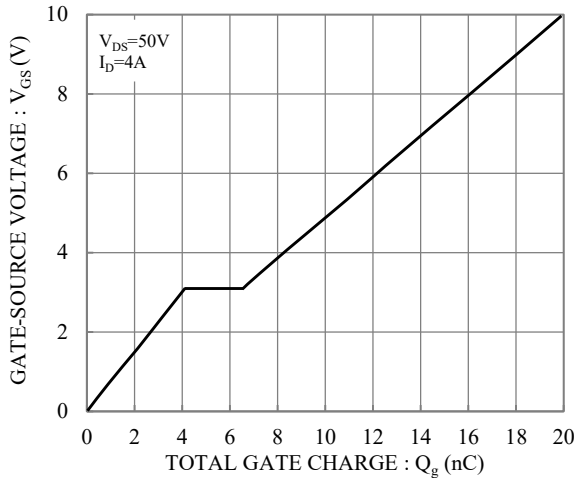
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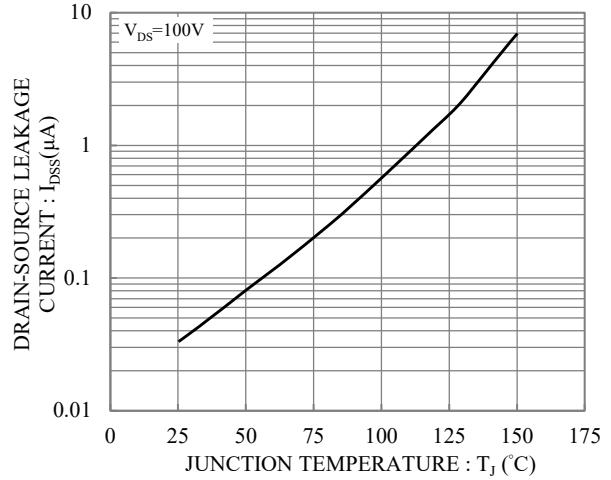
**Fig.7 Drain-Source On-State Resistance vs. Junction Temperature**



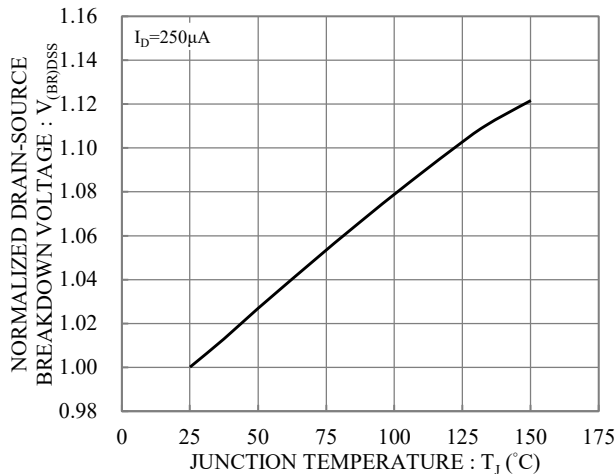
**Fig.8 Capacitance vs. Drain-Source Voltage**



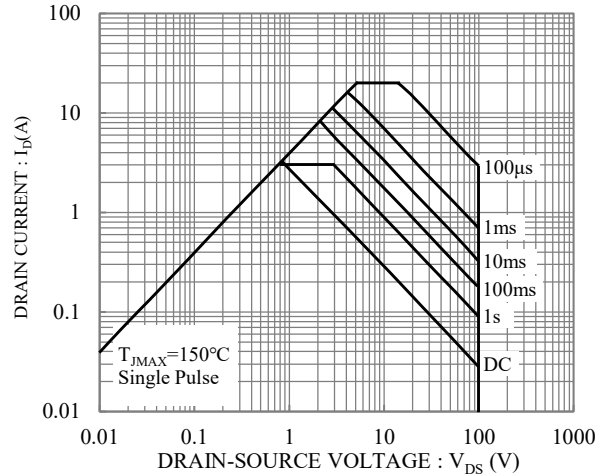
**Fig.9 Gate Charge**



**Fig.10 Drain-Source Leakage Current vs. Junction Temperature**



**Fig.11 Brekdown Voltage vs. Junction Temperature**



**Fig.12 Safe Operation Area**



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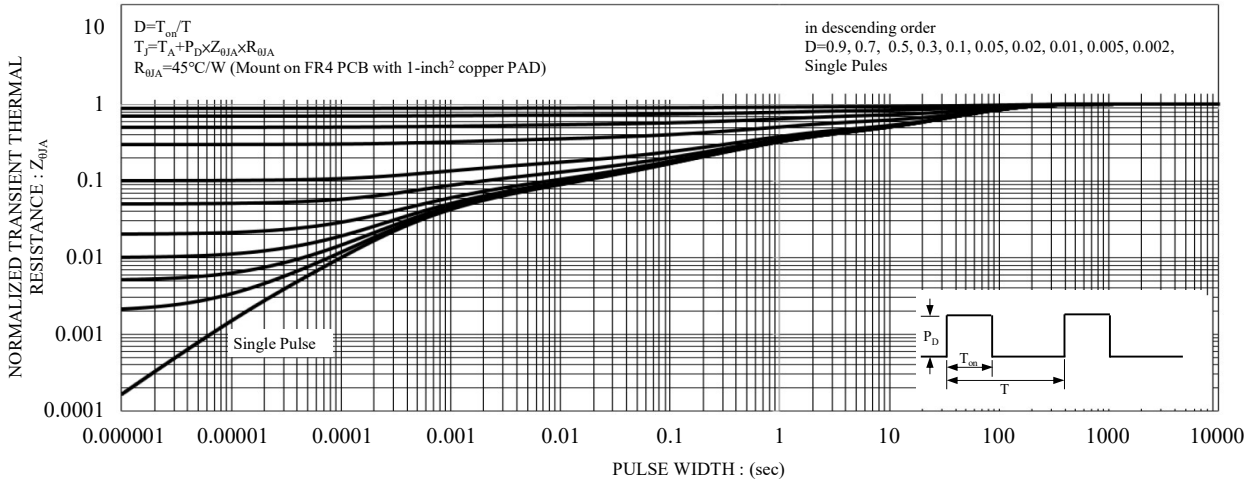


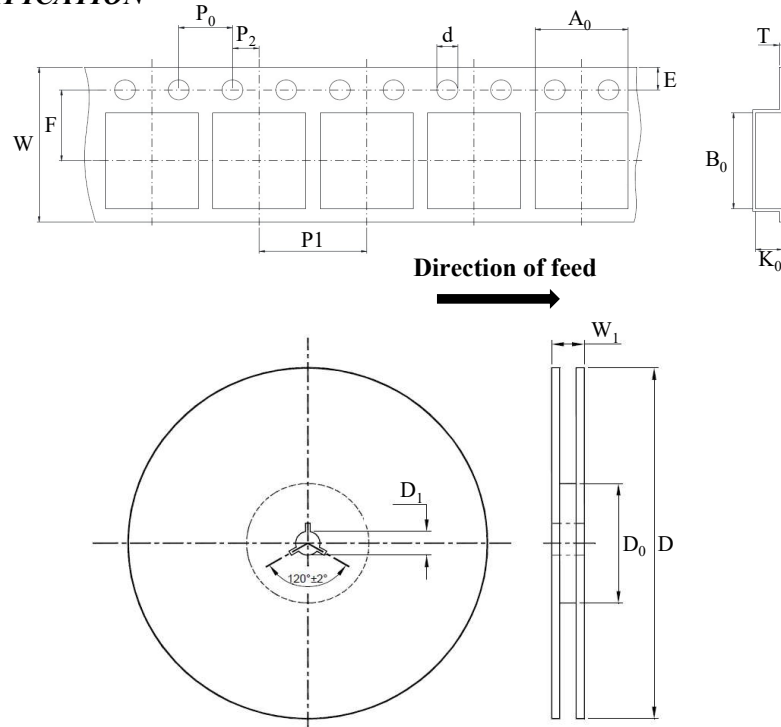
Fig.13 Maximum Transient Thermal Impedance



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## TAPE & REEL SPECIFICATION



Item	Symbol	SOT-223
Carrier width	A <sub>0</sub>	7.05 ± 0.10
Carrier length	B <sub>0</sub>	7.45 ± 0.10
Carrier depth	K <sub>0</sub>	1.95 ± 0.10
Sprocket hole	d	1.50 ± 0.10
Reel outside diameter	D	330.00 ± 2.00
Feed hole width	D <sub>0</sub>	100.00
Reel inner diameter	D <sub>1</sub>	16.40 ± 0.50
Sprocket hole position	E	1.75 ± 0.10
Punch hole position	F	5.50 ± 0.10
Sprocket hole pitch	P <sub>0</sub>	4.00 ± 0.10
Punch hole pitch	P <sub>1</sub>	8.00 ± 0.10
Embossment center	P <sub>2</sub>	2.00 ± 0.10
Overall tape thickness	T	0.25 ± 0.05
Tape width	W	12.00 ± 0.20
Reel width	W <sub>1</sub>	MAX. 20.00

## ORDER INFORMATION

Part Number	Marking Code	Reel Size	Quantity
SMTQ10N1K1LSSEH	TQ10N1K1LS	13"	3,000



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## **SUGGESTED SOLDER PAD LAYOUT**

